

## **AMENDMENTS**

### **In the Specification:**

On Page 15, lines 1-23, amend the paragraph as follows:

tricyclohexylphosphine, triphenylphosphine(TPP), tribenzylphosphine, tritolylphosphine, p-styrylphosphine, tris(2,6-dimethoxyphenyl)phosphine, tri-4-methylphenylphosphine, tri-2-cyanoethylphosphine and the like, bis(diphenylphosphino)methane, 1,2-bis(diphenylphosphino)ethane, 1,4-bis-(diphenylphosphino)butane, triphenylphosphine-triphenylborane, tetraphenylphosphonium tetraphenylborate and the like), imidazole curing accelerators (e.g., 2-methylimidazole, 2-ethyl-4-methylimidazole, 2-phenyl-4-methylimidazole, 1-benzyl-2-methylimidazole, 2-ethylimidazole, 2-isopropylimidazole, 2-undecylimidazole, 1-cyanoethyl-2-methylimidazole, 1-cyanoethyl-2-ethyl-4-methylimidazole, 1-cyanoethyl-2-undecylimidazole, 1-cyanoethyl-2-isopropylimidazole, 1-cyanoethyl-2-phenylimidazole), and the like can be mentioned. The curing accelerator is not limited to these and various curing accelerators can be used. These curing accelerators can be used alone or in a mixture thereof as necessary. The amount of the curing accelerator to be added can be appropriately selected from the range of 0.1-10 wt% relative to the total amount of the curable composition, so that an appropriate curing performance can be obtained in consideration of the epoxy compound (a) and amine compound (b) to be used.